

## Description

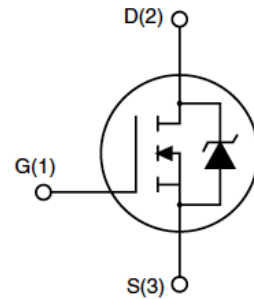
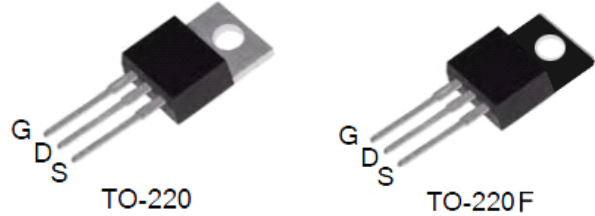
### Features

$V_{DSS}$	$R_{DS(ON)}$ @ 10V (typ)	$I_D$
650V	0.65Ω	12A

- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

### Application

- Active power factor correction
- Uninterruptible Power Supply (UPS)
- Electronic lamp ballasts



## Absolute Maximum Ratings $T_C=25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter		TO-220	TO-220F	Units
$V_{DSS}$	Drain-Source Voltage		650		V
$V_{GSS}$	Gate-Source Voltage		± 30		V
$I_D$	Continuous Drain Current	$T_C = 25^\circ\text{C}$	12	12*	A
		$T_C = 100^\circ\text{C}$	7.5	7.5*	A
$I_{DM}$	Pulsed Drain Current <sup>note1</sup>		48	48*	A
$E_{AS}$	Single Pulsed Avalanche Energy <sup>note2</sup>		320		mJ
dv/dt	Peak Diode Recovery Energy <sup>note3</sup>		4.5		V/ns
$P_D$	Power Dissipation	$T_C = 25^\circ\text{C}$	160	50	W
	Linear Derating Factor	$T_C > 25^\circ\text{C}$	1.33	0.4	W/°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case		0.75	2.5	°C/W
$T_J, T_{STG}$	Operating and Storage Temperature Range		-55 to +150		°C

\*Drain current limited by maximum junction temperature

## Electrical Characteristics $T_C=25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	650	-	-	V
$\frac{\Delta V_{(BR)DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D = 250\mu A$	-	0.68	-	$V/^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 650V, V_{GS} = 0V$	-	-	1	$\mu A$
		$V_{DS} = 520V, T_C = 125^\circ\text{C}$	-	-	10	$\mu A$
$I_{GSS}$	Gate to Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 30V$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(th)}$	Gate Threshold Voltage <sup>note4</sup>	$V_{DS} = V_{GS}, I_D = 250\mu A$	2	-	4	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = 10V, I_D = 6A$	-	0.65	0.75	$\Omega$
$g_{FS}$	Forward Transconductance	$V_{DS} = 30V, I_D = 6A$	-	5	-	S
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS} = 25V, V_{GS} = 0V,$ $f = 1.0\text{MHz}$	-	1834	-	pF
$C_{oss}$	Output Capacitance		-	168	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	13.3	-	pF
$Q_g$	Total Gate Charge	$V_{DD} = 520V, I_D = 12A,$ $V_{GS} = 10V$	-	44.4	-	nC
$Q_{gs}$	Gate-Source Charge		-	8.4	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge		-	15.7	-	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 325V, I_D = 12A,$ $R_G = 10\Omega, V_{GS} = 10V$	-	24.9	-	ns
$t_r$	Turn-On Rise Time		-	25.7	-	ns
$t_{d(off)}$	Turn-Off Delay Time		-	78.3	-	ns
$t_f$	Turn-Off Fall Time		-	37.1	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_S$	Maximum Continuous Drain to Source Diode Forward Current		-	-	12	A
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current		-	-	48	A
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS} = 0V, I_S = 12A$	-	-	1.4	V
$t_{rr}$	Reverse Recovery Time	$V_{GS} = 0V, I_F = 12A,$	-	585	-	ns
$Q_{rr}$	Reverse Recovery Charge	$di/dt = 100A/\mu s$	-	4.2	-	$\mu C$

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2.  $L = 10\text{mH}, I_{AS} = 8A, V_{DD} = 50V, R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$
3.  $I_{SD} \leq 12A, di/dt \leq 200A/\mu s, V_{DD} \leq B_{VDSS}$ , Starting  $T_J = 25^\circ\text{C}$
4. Pulse width  $\leq 300\mu s$ ; duty cycle  $\leq 2\%$ .

## Typical Performance Characteristics

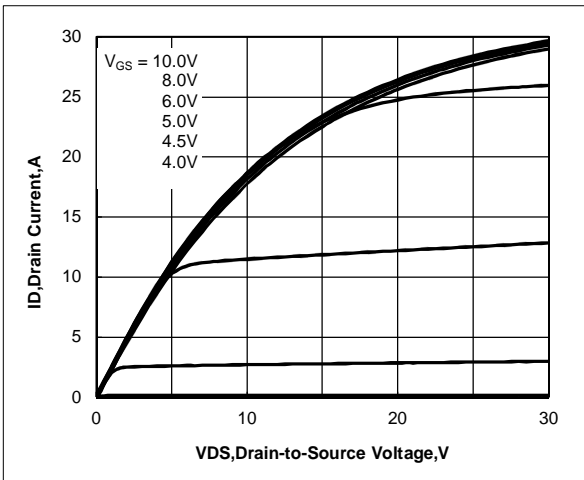


Figure 1. Output Characteristics

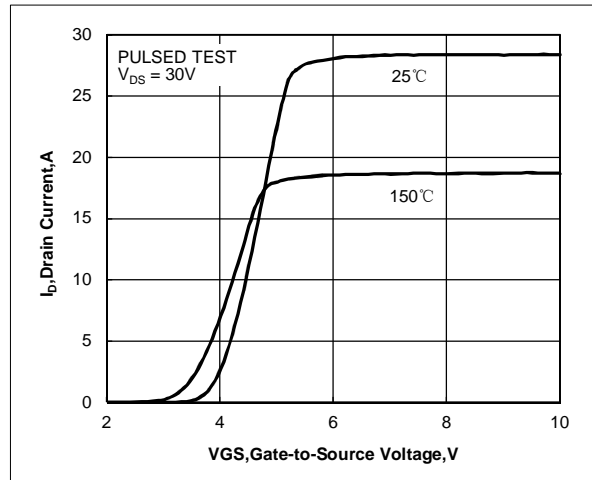


Figure 2. Transfer Characteristics

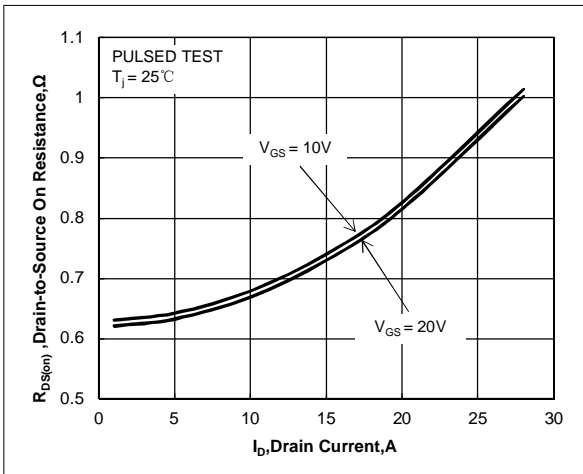


Figure 3. Drain-to-Source On Resistance vs. Drain Current and Gate Voltage

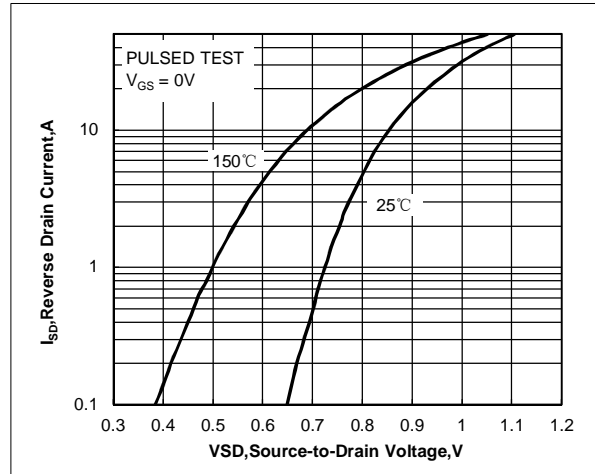


Figure 4. Body Diode Forward Voltage vs. Source Current and Temperature

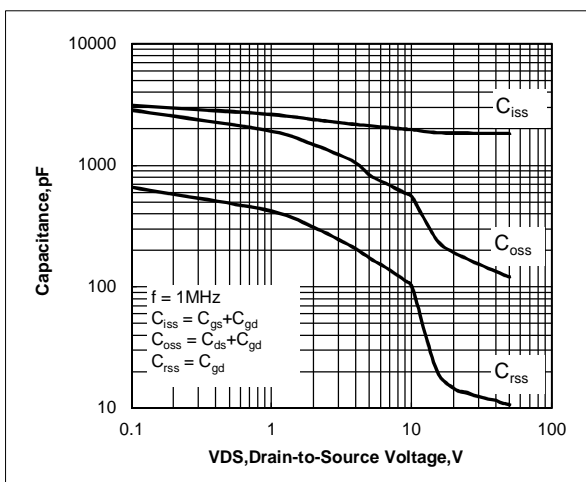


Figure 5. Capacitance Characteristics

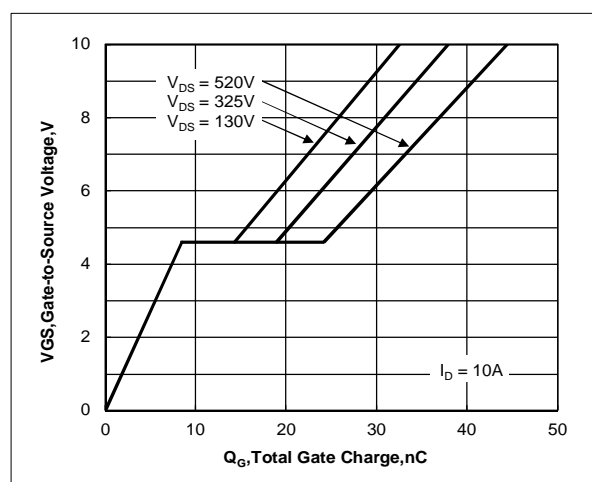
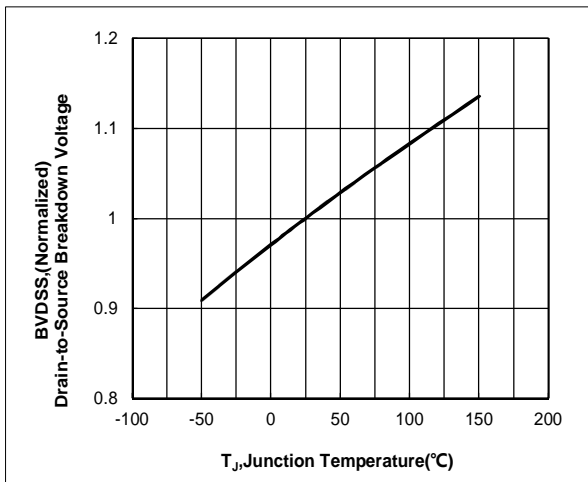
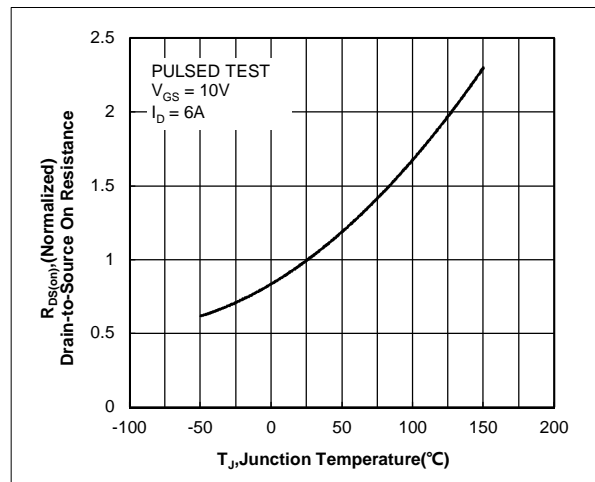


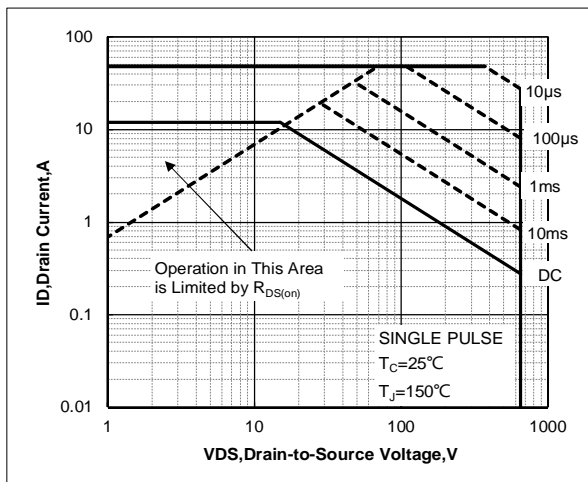
Figure 6. Gate Charge Characteristics



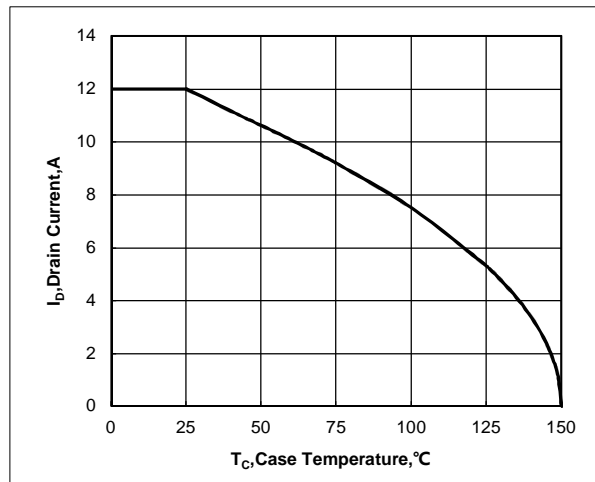
**Figure 7. Normalized Breakdown Voltage vs. Junction Temperature**



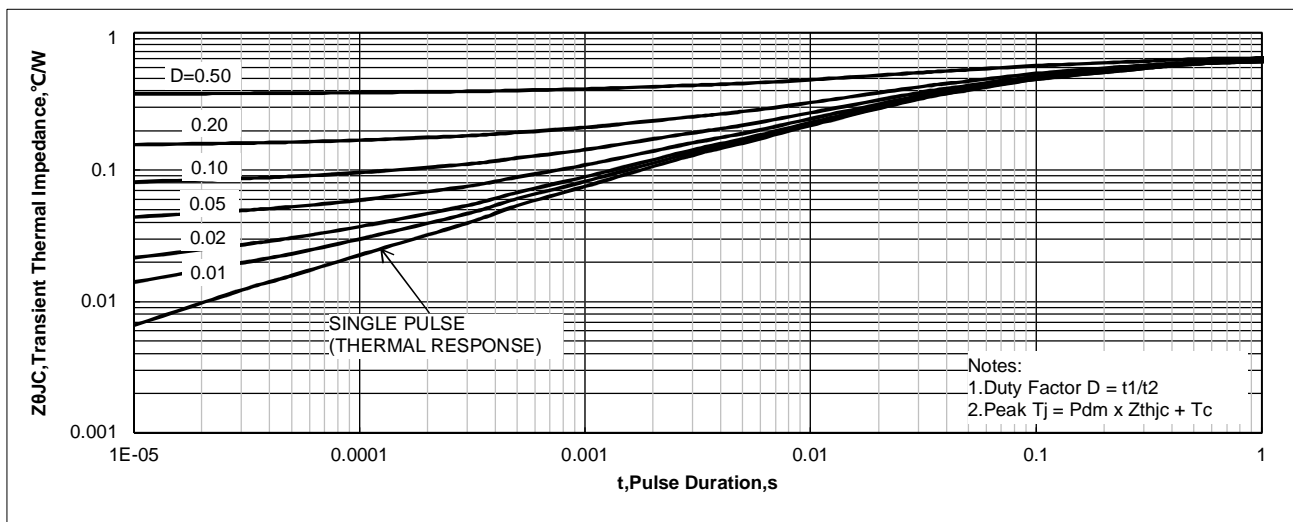
**Figure 8. Normalized On Resistance vs. Junction Temperature**



**Figure 9. Maximum Safe Operating Area**



**Figure 10. Maximum Continuous Drain Current vs. Case Temperature**



**Figure 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case**

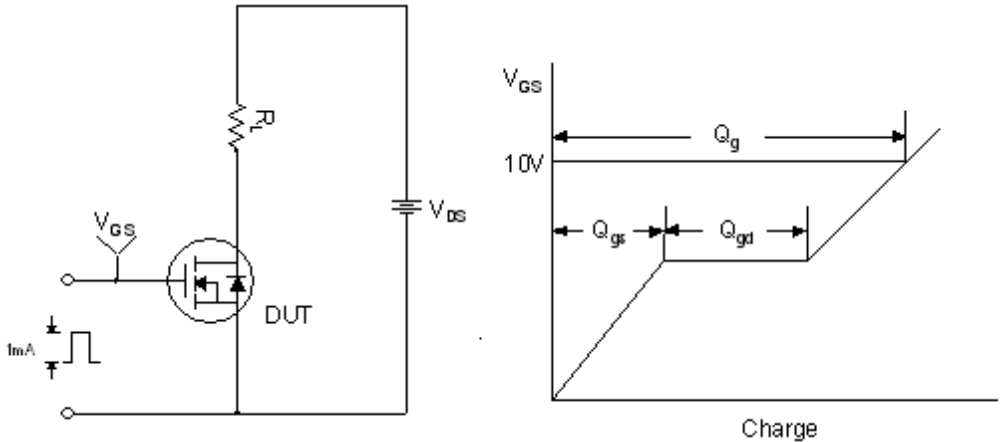


Figure 12. Gate Charge Test Circuit & Waveform

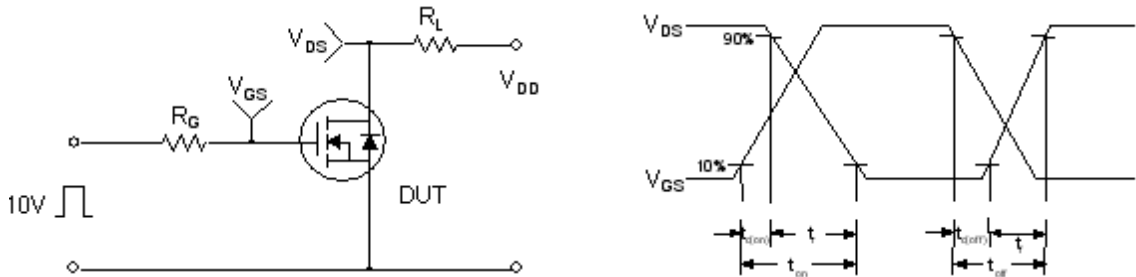


Figure 13. Resistive Switching Test Circuit & Waveforms

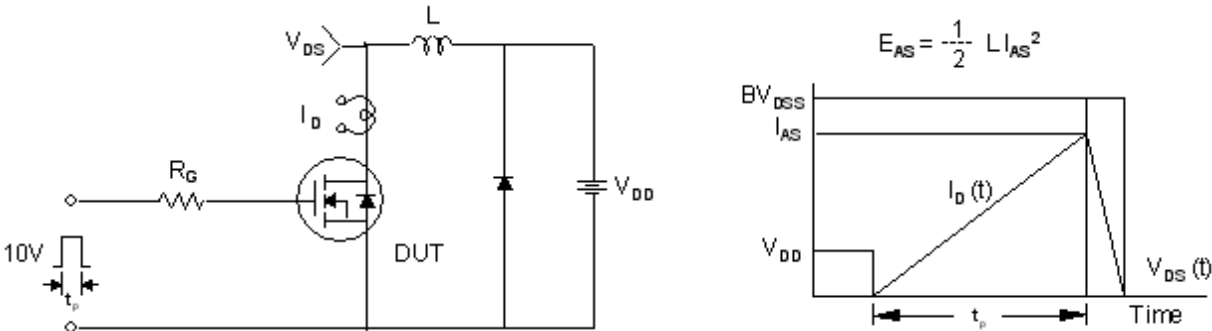


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

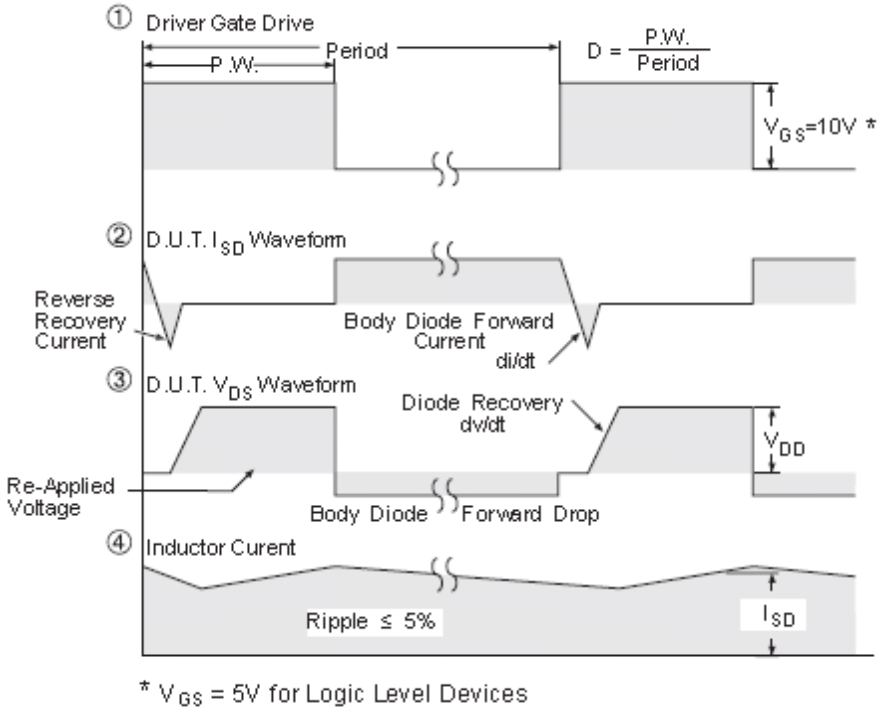
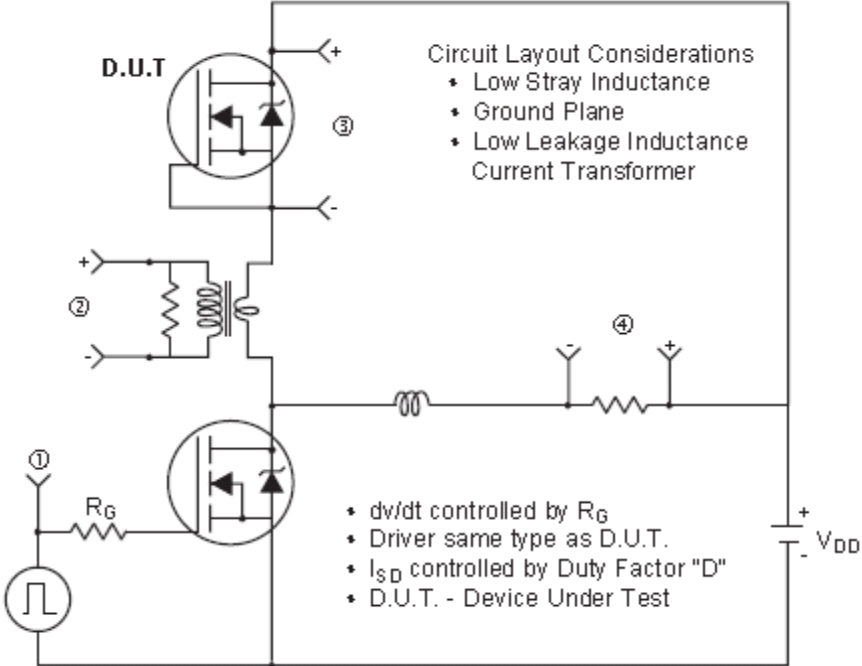


Figure 15. Peak Diode Recovery  $dv/dt$  Test Circuit & Waveforms (For N-channel)